

# N-Channel 150 V (D-S) MOSFET

| PRODUCT SUMMARY     |                                  |                    |  |  |  |
|---------------------|----------------------------------|--------------------|--|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)          | I <sub>D</sub> (A) |  |  |  |
| 150                 | 0.241 at V <sub>GS</sub> = 10 V  | 6                  |  |  |  |
|                     | 0.250 at V <sub>GS</sub> = 4.5 V | 4                  |  |  |  |

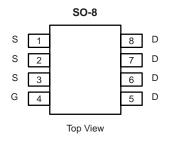
#### FEATURES

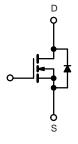
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> Tested



#### **APPLICATIONS**

• Primary Side Switch





N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted) |   |                                   |                  |    |  |  |
|--|---|-----------------------------------|------------------|----|--|--|
| Parameter  | Symbol  | Limit                             | Unit             |    |  |  |
| Drain-Source Voltage   | V <sub>DS</sub>                                   | 150                               | - v              |    |  |  |
| Gate-Source Voltage  | V <sub>GS</sub>                                   | ± 20                              |                  |    |  |  |
| Continuous Drain Current $(T_1 = 175 \ ^{\circ}C)^{b}$                           | T <sub>C</sub> = 25 °C<br>T <sub>C</sub> = 125 °C | 1_                                | 6                |    |  |  |
| Commuous Drain Current $(T_j = 175 \text{ C})^2$                                 | T <sub>C</sub> = 125 °C                           | I <sub>D</sub>                    | 4.7              |    |  |  |
| Pulsed Drain Current   | I <sub>DM</sub>                                   | 25                                | А                |    |  |  |
| Continuous Source Current (Diode Conduction)                                     | ۱ <sub>S</sub>                                    | 5.2                               | 1                |    |  |  |
| Avalanche Current  | I <sub>AR</sub>                                   | 4.5                               | 7                |    |  |  |
| Repetitive Avalanche Energy (Duty Cycle $\leq$ 1 %)                              | L = 0.1 mH  | E <sub>AR</sub>                   | 11.3             | mJ |  |  |
| Manimum David Disain ation   | T <sub>C</sub> = 25 °C                            | P                                 | 62 <sup>b</sup>  | W  |  |  |
| Maximum Power Dissipation  | T <sub>A</sub> = 25 °C                            | P <sub>D</sub>                    | 2.7 <sup>a</sup> | V  |  |  |
| Operating Junction and Storage Temperature Range                                 |   | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C |  |  |

| THERMAL RESISTANCE RATINGS       |              |                     |         |         |      |  |  |
|----------------------------------|--------------|---------------------|---------|---------|------|--|--|
| Parameter                        |              | Symbol              | Typical | Maximum | Unit |  |  |
| hungtion to Ambienta             | t ≤ 10 s     | - R <sub>thJA</sub> | 16      | 20      | °C/W |  |  |
| Junction-to-Ambient <sup>a</sup> | Steady State |                     | 45      | 55      |      |  |  |
| Junction-to-Case                 |              | R <sub>thJC</sub>   | 2       | 2.4     |      |  |  |

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

# DTM5106

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| Parameter                                     | Symbol              | Test Conditions Min  |     | Typ. <sup>a</sup> | Max.  | Unit |  |
|---|---------------------|--|-----|-------------------|-------|------|--|
| Static  |                     |  |     |                   |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>     | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$  | 150 |                   |       | V    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$   | 2   |                   |       | V    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 V, V_{GS} = \pm 20 V$  |     |                   | ± 100 | nA   |  |
|   |                     | V <sub>DS</sub> = 150 V, V <sub>GS</sub> = 0 V   |     |                   | 1     | μA   |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> = 150 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                    |     |                   | 50    |      |  |
|   |                     | V <sub>DS</sub> = 150 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C                    |     |                   | 250   | 1    |  |
| On-State Drain Current <sup>b</sup>           | I <sub>D(on)</sub>  | $V_{DS} = 5 V, V_{GS} = 10 V$  | 15  |                   |       | А    |  |
|   |                     | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2 A   |     | 0.241             | 0.263 | Ω    |  |
| - ·   | Р                   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2 A, T <sub>J</sub> = 125 °C                      |     | 0.249             | 0.273 |      |  |
| Drain-Source On-State Resistance <sup>b</sup> | R <sub>DS(on)</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2 A, T <sub>J</sub> = 175 °C                      |     | 0.280             | 0.302 |      |  |
|   |                     | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2 \text{ A}$                                      |     | 0.250             | 0.275 |      |  |
| Forward Transconductance <sup>b</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 2 A   |     | 25                |       | S    |  |
| Dynamic <sup>a</sup>                          |                     | ·  |     |                   |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>    |  |     | 900               |       | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>    | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz                                   |     | 115               |       |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |  |     | 70                |       |      |  |
| Total Gate Charge <sup>c</sup>                | Qg                  |  |     | 20                | 25    |      |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>     | $V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 2 \text{ A}$        |     | 5.5               |       | nC   |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>     |  |     | 7                 |       |      |  |
| Gate Resistance                               | Rg                  |  | 1   |                   | 3.2   | Ω    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>  |  |     | 8                 | 12    |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>      | $V_{DD}$ = 75 V, $R_L$ = 5 $\Omega$  |     | 35                | 55    |      |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub> | $I_D \cong 2 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{G}} = 2.5$ |     | 17                | 25    | ns   |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>      | Ω  |     | 30                | 45    |      |  |
| Source-Drain Diode Ratings and Cha            | racteristic (T      | <sub>C</sub> = 25 °C)  |     |                   |       |      |  |
| Pulsed Current                                | I <sub>SM</sub>     |  |     |                   | 6     | А    |  |
| Diode Forward Voltage <sup>b</sup>            | V <sub>SD</sub>     | I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V  |     | 0.9               | 1.5   | V    |  |
| Source-Drain Reverse Recovery Time            | t <sub>rr</sub>     | I <sub>F</sub> = 2 A, dl/dt = 100 A/µs   |     | 55                | 85    | ns   |  |

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

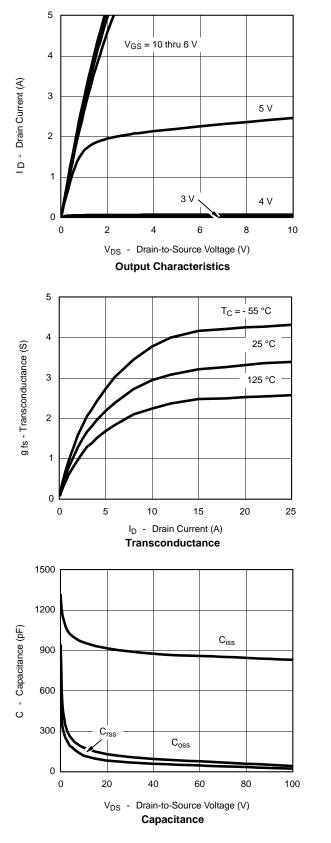
c. Independent of operating temperature.

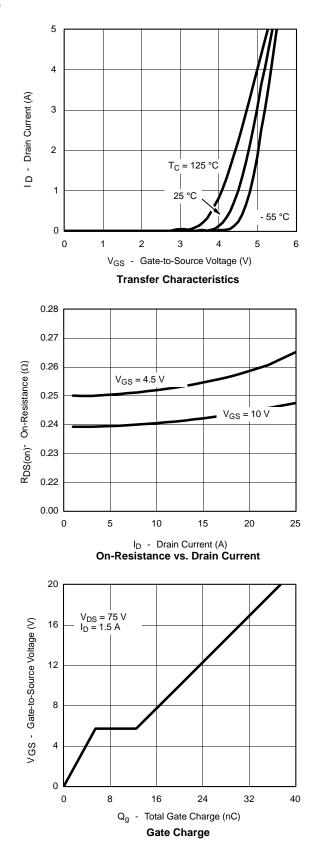
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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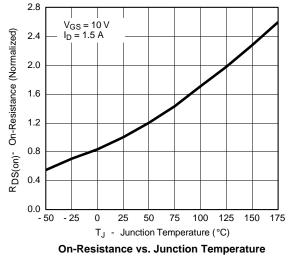
#### TYPICAL CHARACTERISTICS (25 °C unless noted)





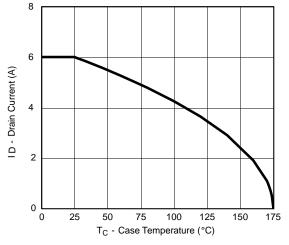
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#### TYPICAL CHARACTERISTICS (25 °C unless noted)

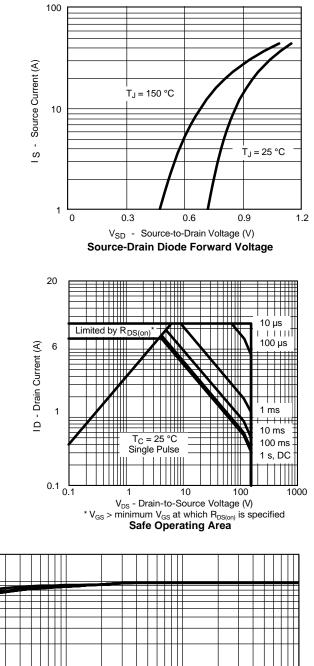


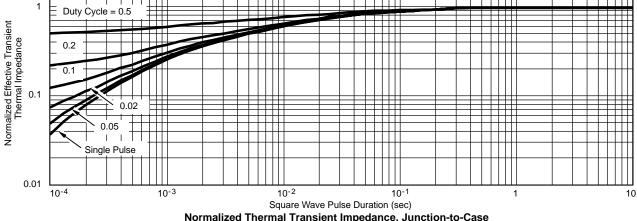
**THERMAL RATINGS** 

2



**Maximum Avalanche Drain Current** vs. Case Temperature





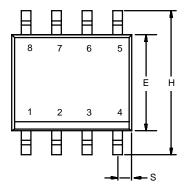
Normalized Thermal Transient Impedance, Junction-to-Case

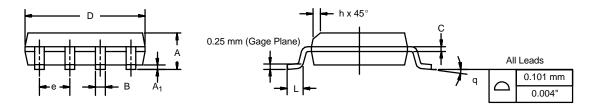


# Package Information www.din-tek.jp

### SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

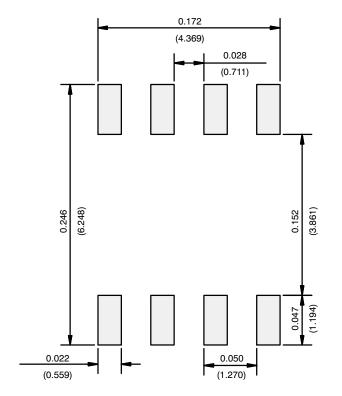




|   | MILLIM | IETERS | INC       | IES   |  |  |
|---|--------|--------|-----------|-------|--|--|
| DIM   | Min    | Мах    | Min       | Max   |  |  |
| A   | 1.35   | 1.75   | 0.053     | 0.069 |  |  |
| A <sub>1</sub>                              | 0.10   | 0.20   | 0.004     | 0.008 |  |  |
| В   | 0.35   | 0.51   | 0.014     | 0.020 |  |  |
| С   | 0.19   | 0.25   | 0.0075    | 0.010 |  |  |
| D   | 4.80   | 5.00   | 0.189     | 0.196 |  |  |
| E   | 3.80   | 4.00   | 0.150     | 0.157 |  |  |
| е   | 1.27   | BSC    | 0.050 BSC |       |  |  |
| н   | 5.80   | 6.20   | 0.228     | 0.244 |  |  |
| h   | 0.25   | 0.50   | 0.010     | 0.020 |  |  |
| L   | 0.50   | 0.93   | 0.020     | 0.037 |  |  |
| q   | 0°     | 8°     | 0°        | 8°    |  |  |
| S   | 0.44   | 0.64   | 0.018     | 0.026 |  |  |
| ECN: C-06527-Rev. I, 11-Sep-06<br>DWG: 5498 |        |        |           |       |  |  |



#### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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